

BLC10G27XS-551AVT

Power LDMOS transistor

Rev. 1 — 20 September 2019

AMPLEON

Product data sheet

1. Product profile

1.1 General description

550 W LDMOS packaged asymmetric Doherty power transistor for base station applications at frequencies from 2620 MHz to 2690 MHz.

Table 1. Typical performance

Typical RF performance at $T_{case} = 25\text{ °C}$ in an asymmetrical Doherty demo circuit. $V_{DS} = 32\text{ V}$; $I_{DQ} = 1000\text{ mA}$ (main); $V_{GS(amp)peak} = 0.85\text{ V}$, unless otherwise specified.

Test signal	f	V_{DS}	$P_{L(AV)}$	G_p	η_D	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
1-carrier W-CDMA	2620 to 2690	32	91	13.5	46	-31.3 [1]

[1] Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.9 dB at 0.01 % probability on CCDF.

1.2 Features and benefits

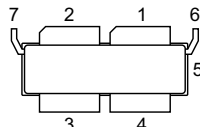
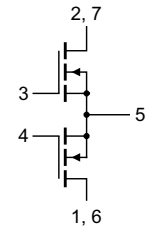
- Excellent ruggedness
- High efficiency
- Low thermal resistance providing excellent thermal stability
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent digital pre-distortion capability
- Internally matched for ease of use
- Integrated ESD protection
- For RoHS compliance see the product details on the Ampleon website

1.3 Applications

- RF power amplifiers for base stations and multi carrier applications in the 2620 MHz to 2690 MHz frequency range

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	drain2 (peak)		
2	drain1 (main)		
3	gate1 (main)		
4	gate2 (peak)		
5	source ^[1]		
6	video decoupling (peak)		
7	video decoupling (main)		

[1] Connected to flange.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLC10G27XS-551AVT	-	air cavity plastic earless flanged package; 6 leads	SOT1258-4

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	65	V
$V_{GS(amp)main}$	main amplifier gate-source voltage		-6	+9	V
$V_{GS(amp)peak}$	peak amplifier gate-source voltage		-6	+9	V
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature	^[1]	-	225	°C
T_{case}	case temperature	operating ^[1]	-40	+125	°C

[1] Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$V_{DS} = 32$ V; $I_{Dq} = 1000$ mA (main); $V_{GS(amp)peak} = 0.885$ V; $T_{case} = 80$ °C		
		$P_L = 87$ W	0.24	k/W
		$P_L = 110$ W	0.22	k/W

6. Characteristics

Table 6. DC characteristics

$T_j = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Main device						
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 1.8\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 180\text{ mA}$	1.6	2.0	2.4	V
V_{GSq}	gate-source quiescent voltage	$V_{DS} = 32\text{ V}; I_D = 1000\text{ mA}$	-	2.2	-	V
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 32\text{ V}$	-	-	2.8	μA
I_{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 2.37\text{ V}; V_{DS} = 10\text{ V}$	-	34	-	A
I_{GSS}	gate leakage current	$V_{GS} = 9\text{ V}; V_{DS} = 0\text{ V}$	-	-	280	nA
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 9.0\text{ A}$	-	20.5	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 2.37\text{ V}; I_D = 6.3\text{ A}$	-	72	108	$\text{m}\Omega$
Peak device						
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 3.8\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 380\text{ mA}$	1.6	2.0	2.4	V
V_{GSq}	gate-source quiescent voltage	$V_{DS} = 32\text{ V}; I_D = 1900\text{ mA}$	-	2.2	-	V
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 32\text{ V}$	-	-	2.8	μA
I_{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 2.37\text{ V}; V_{DS} = 10\text{ V}$	-	57	-	A
I_{GSS}	gate leakage current	$V_{GS} = 9\text{ V}; V_{DS} = 0\text{ V}$	-	-	280	nA
g_{fs}	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 19.0\text{ A}$	-	39.0	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 2.37\text{ V}; I_D = 13.3\text{ A}$	-	37	62	$\text{m}\Omega$

Table 7. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF;
3GPP test model 1; 1 to 64 DPCH; $f_1 = 2622.5\text{ MHz}$; $f_2 = 2687.5\text{ MHz}$; RF performance at
 $V_{DS} = 32\text{ V}$; $I_{Dq} = 1000\text{ mA}$ (main); $V_{GS(amp)peak} = 0.9\text{ V}$; $T_{case} = 25\text{ }^{\circ}\text{C}$; unless otherwise specified;
in an asymmetrical Doherty production test circuit at frequencies from 2620 MHz to 2690 MHz.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	$P_{L(AV)} = 91\text{ W}$	12	13	-	dB
RL_{in}	input return loss	$P_{L(AV)} = 91\text{ W}$	-	-14	-10	dB
η_D	drain efficiency	$P_{L(AV)} = 91\text{ W}$	41	45	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 91\text{ W}$	-	-29	-24	dBc

Table 8. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF;
3GPP test model 1; 1 to 64 DPCH; $f = 2687.5\text{ MHz}$; RF performance at $V_{DS} = 32\text{ V}$;
 $I_{Dq} = 1000\text{ mA}$ (main); $V_{GS(amp)peak} = 0.9\text{ V}$; $T_{case} = 25\text{ }^{\circ}\text{C}$; unless otherwise specified; in an
asymmetrical Doherty production test circuit at a frequency of 2690 MHz.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
PAR_O	output peak-to-average ratio	$P_{L(AV)} = 145\text{ W}$	5.9	6.4	-	dB
$P_{L(M)}$	peak output power	$P_{L(AV)} = 145\text{ W}$	553	628	-	W

7. Test information

7.1 Ruggedness in Doherty operation

The BLC10G27XS-551AVT is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: $V_{DS} = 32$ V; $I_{DQ} = 1000$ mA; $V_{GS(amp)peak} = 0.885$ V; $f = 2620$ MHz; $P_L = 230$ W (5 dB OBO); 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.6 dB at 0.01 % probability on the CCDF.

7.2 Impedance information

Table 9. Typical impedance of main device

Measured load-pull data of main device; $I_{DQ} = 900$ mA (main); $V_{DS} = 32$ V; pulsed CW ($t_p = 100$ μ s; $\delta = 10$ %).

f	Z _S [1]	Z _L [1]	P _L [2]	η_D [2]	G _p [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
Maximum power load					
2500	1.1 – j5.2	1.8 – j4.4	306	59.3	13.9
2600	1.6 – j5.8	1.9 – j4.5	301	60.0	14.1
2690	2.5 – j6.5	2.0 – j4.3	298	60.2	14.2
Maximum drain efficiency load					
2500	1.2 – j5.4	3.9 – j4.5	223	66.7	15.7
2600	1.7 – j6.0	3.8 – j3.3	213	66.4	15.9
2690	2.8 – j6.6	3.1 – j3.0	218	66.1	15.8

[1] Z_S and Z_L defined in [Figure 1](#).

[2] At 3 dB gain compression.

Table 10. Typical impedance of peak device

Measured load-pull data of peak device; $I_{DQ} = 1900$ mA (peak); $V_{DS} = 32$ V; pulsed CW ($t_p = 100$ μ s; $\delta = 10$ %).

f	Z _S [1]	Z _L [1]	P _L [2]	η_D [2]	G _p [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
Maximum power load					
2500	1.1 – j5.5	2.9 – j4.8	560	56.8	12.7
2600	1.5 – j6.3	2.9 – j4.3	553	57.2	13.0
2690	2.5 – j7.3	2.7 – j4.2	544	55.7	13.0
Maximum drain efficiency load					
2500	1.0 – j5.5	4.1 – j3.0	469	56.7	14.0
2600	1.6 – j6.3	3.4 – j2.4	447	56.5	14.1
2690	2.6 – j7.4	2.6 – j2.6	442	56.5	14.2

[1] Z_S and Z_L defined in [Figure 1](#).

[2] At 3 dB gain compression.

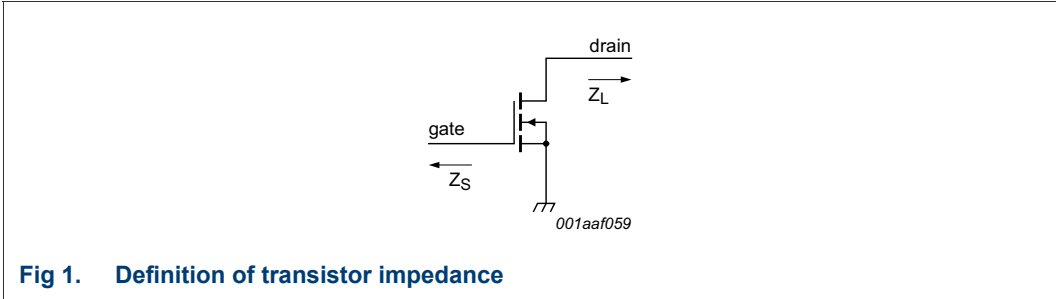
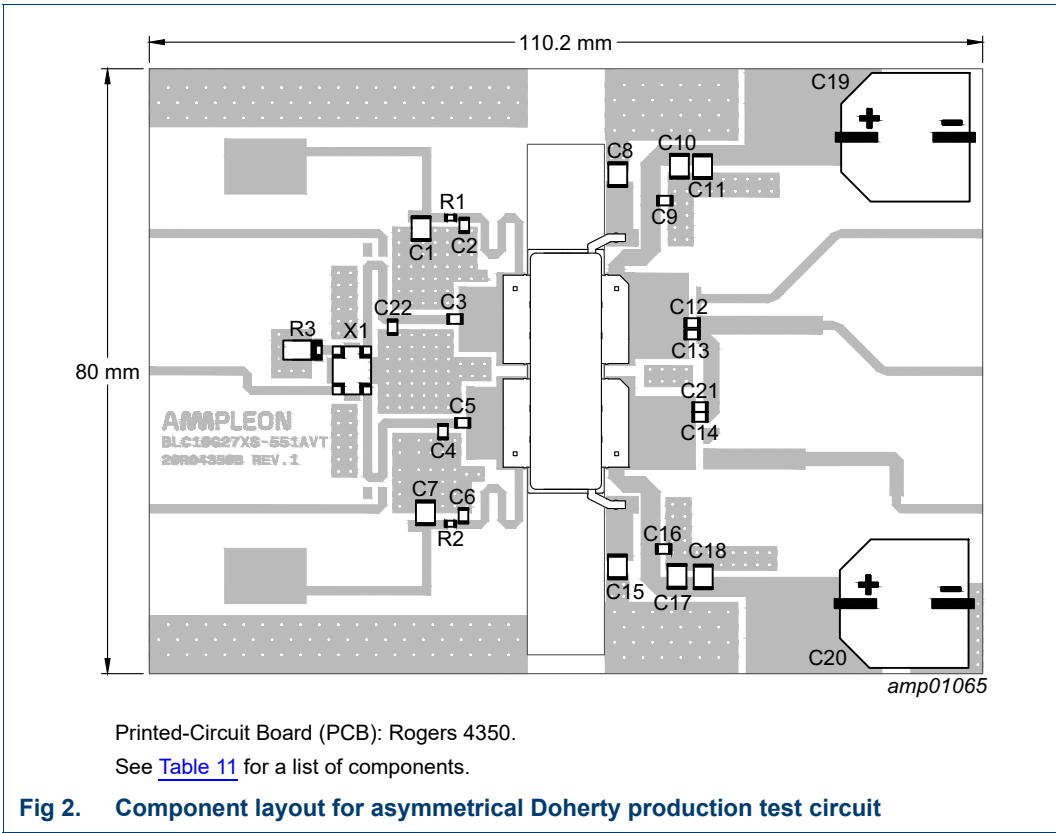


Fig 1. Definition of transistor impedance

7.3 Test circuit



Printed-Circuit Board (PCB): Rogers 4350.

See [Table 11](#) for a list of components.

Fig 2. Component layout for asymmetrical Doherty production test circuit

Table 11. List of components

For test circuit see [Figure 2](#).

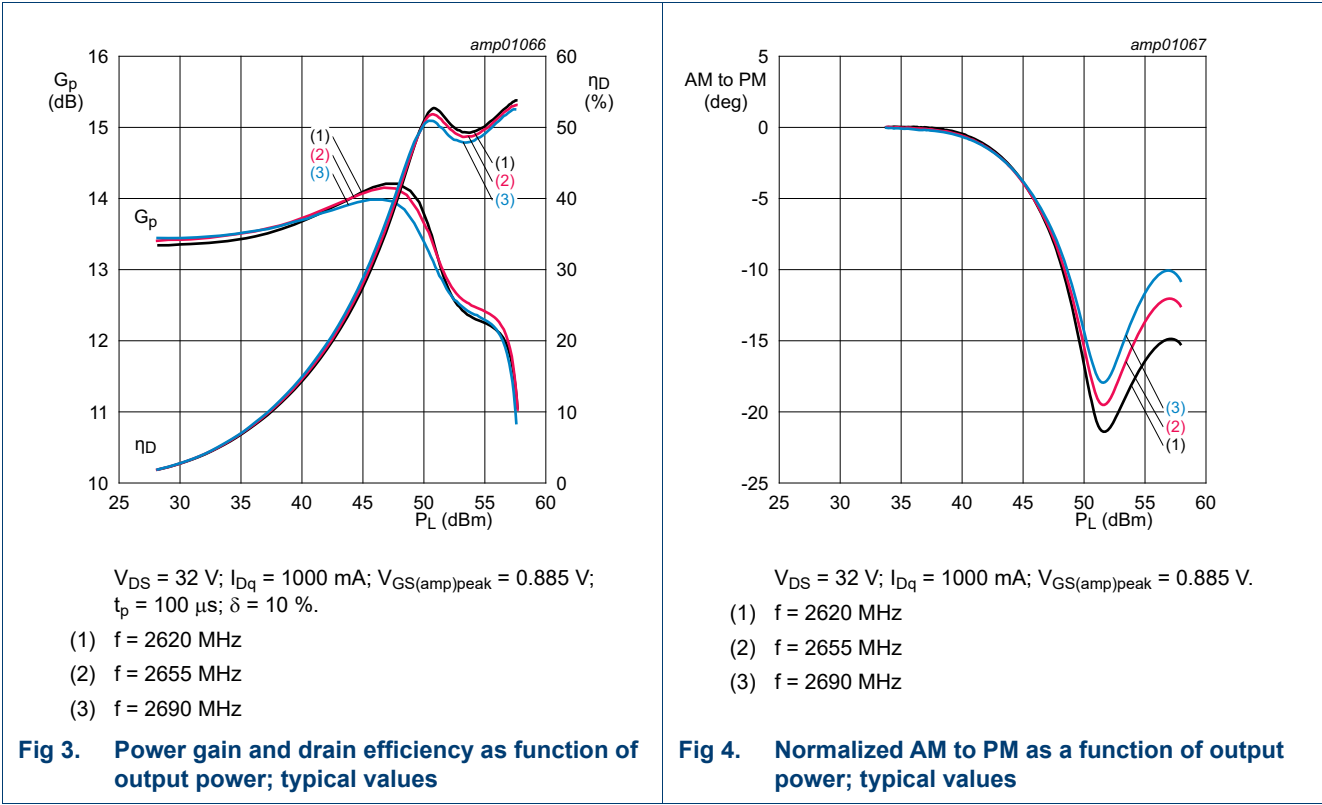
Component	Description	Value	Remarks
C1, C7, C8, C10, C11, C15, C17, C18	multilayer ceramic chip capacitor	10 μ F, 100 V	Murata: 1210
C2, C3, C5, C6, C9, C16	multilayer ceramic chip capacitor	6.8 pF	Murata: HiQ 0805
C4	multilayer ceramic chip capacitor	0.2 pF	ATC 800A/8800B
C14, C21	multilayer ceramic chip capacitor	2.7 pF	Murata: HiQ 0805
C22	multilayer ceramic chip capacitor	0.3 pF	ATC 800A/8800B
C12, C13	multilayer ceramic chip capacitor	3.6 pF	Murata: HiQ 0805
C19, C20	multilayer ceramic chip capacitor	470 μ F, 63 V	EEVFK1J471M

Table 11. List of components ...continued
For test circuit see [Figure 2](#).

Component	Description	Value	Remarks
R1, R2	resistor	4.7 Ω, 1 %	SMD 0805
R3	resistor	50 Ω, 16 W	Anaren: C16A50Z4
X1	hybrid coupler	2 dB, 90°	Anaren: Xinger III, X3C25P1-02S

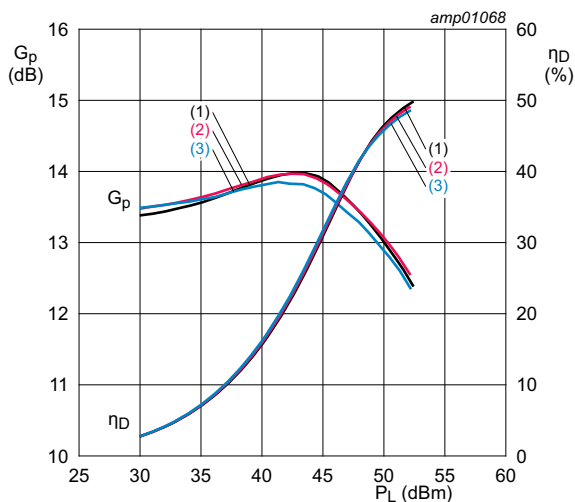
7.4 Graphical data

7.4.1 Pulsed CW



7.4.2 1-Carrier W-CDMA

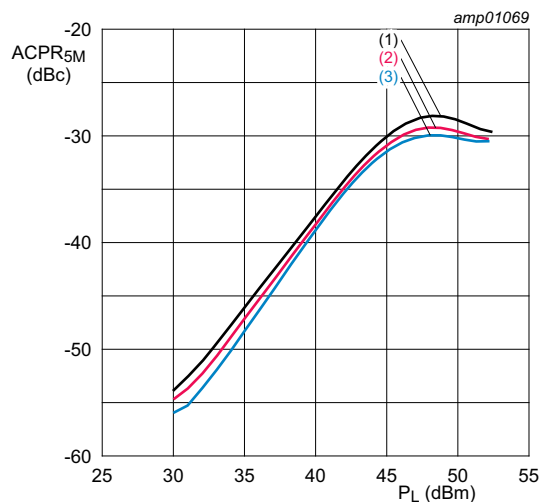
Test signal: 3GPP test model 1; 1 to 64 DPCH (100 % clipping); PAR = 9.9 dB at 0.01 % probability on CCDF per carrier.



$V_{DS} = 32 \text{ V}$; $I_{Dq} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.885 \text{ V}$.

- (1) $f = 2620 \text{ MHz}$
- (2) $f = 2655 \text{ MHz}$
- (3) $f = 2690 \text{ MHz}$

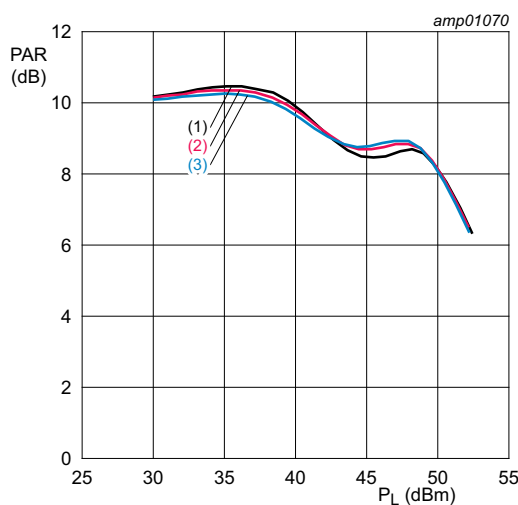
Fig 5. Power gain and drain efficiency as function of output power; typical values



$V_{DS} = 32 \text{ V}$; $I_{Dq} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.885 \text{ V}$.

- (1) $f = 2620 \text{ MHz}$
- (2) $f = 2655 \text{ MHz}$
- (3) $f = 2690 \text{ MHz}$

Fig 6. Adjacent channel power ratio (5 MHz) as a function of output power; typical values



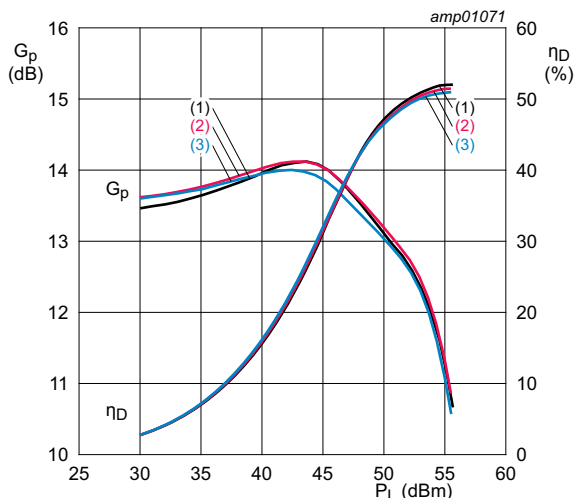
$V_{DS} = 32 \text{ V}$; $I_{Dq} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.885 \text{ V}$.

- (1) $f = 2620 \text{ MHz}$
- (2) $f = 2655 \text{ MHz}$
- (3) $f = 2690 \text{ MHz}$

Fig 7. Peak-to-average power ratio as a function of output power; typical values

7.4.3 1-Carrier LTE

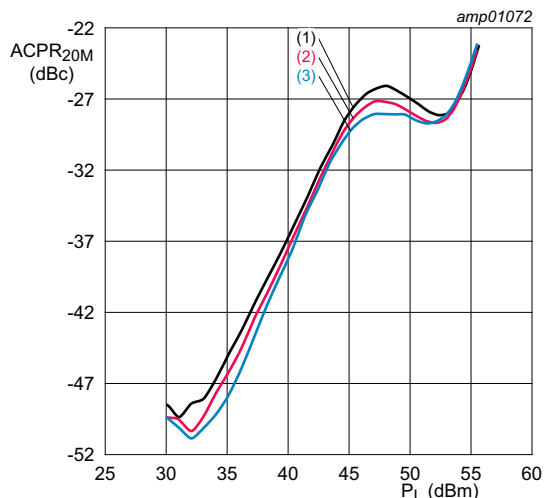
Test signal: 1-carrier LTE 10 MHz; PAR = 6.8 dB at 0.01 % probability on CCDF.



$V_{DS} = 32 \text{ V}$; $I_{DQ} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.885 \text{ V}$.

- (1) $f = 2620 \text{ MHz}$
- (2) $f = 2655 \text{ MHz}$
- (3) $f = 2690 \text{ MHz}$

Fig 8. Power gain and drain efficiency as function of output power; typical values

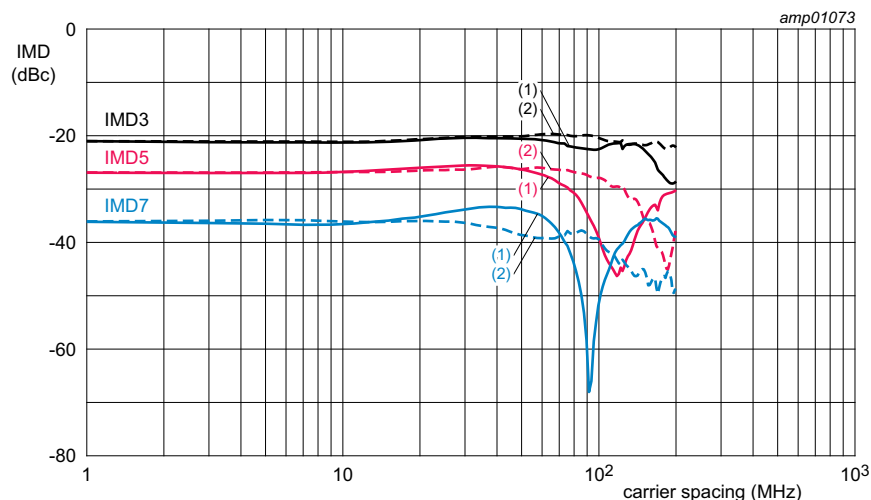


$V_{DS} = 32 \text{ V}$; $I_{DQ} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.885 \text{ V}$.

- (1) $f = 2620 \text{ MHz}$
- (2) $f = 2655 \text{ MHz}$
- (3) $f = 2690 \text{ MHz}$

Fig 9. Adjacent channel power ratio (20 MHz) as a function of output power; typical values

7.4.4 2-Tone VBW

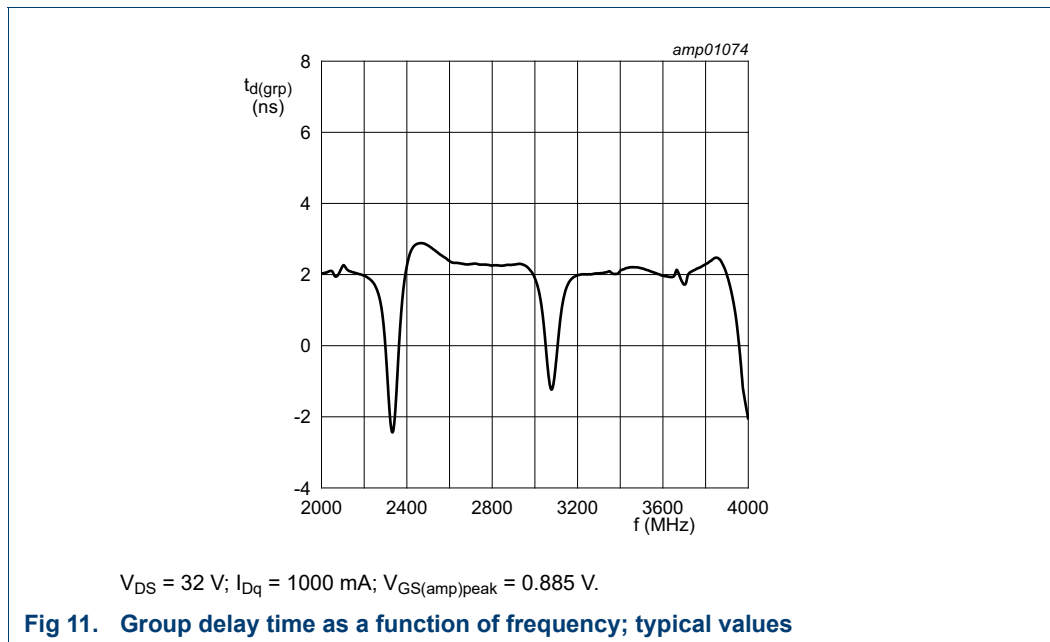


$V_{DS} = 32 \text{ V}$; $I_{DQ} = 1000 \text{ mA}$; $V_{GS(amp)peak} = 0.885 \text{ V}$; $PL = 49.6 \text{ dBm}$; $f = 2620 \text{ MHz}$

- (1) IMD low
- (2) IMD high

Fig 10. VBW capability

7.4.5 Group delay



8. Package outline

Air cavity plastic earless flanged package; 6 leads

SOT1258-4

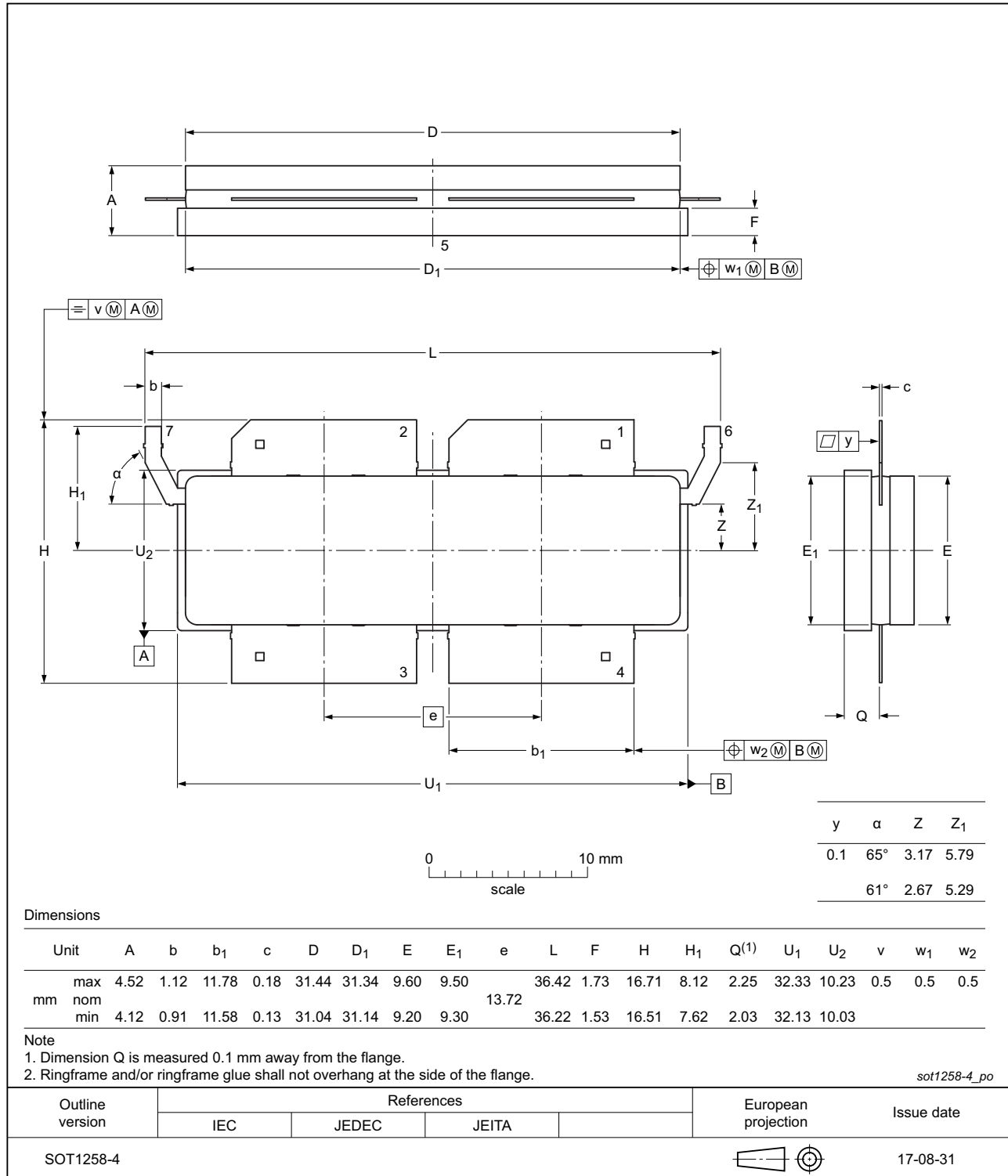


Fig 12. Package outline SOT1258-4

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

Table 12. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C3 [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

[1] CDM classification C3 is granted to any part that passes after exposure to an ESD pulse of 1000 V.

[2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V.

10. Abbreviations

Table 13. Abbreviations

Acronym	Description
3GPP	3rd Generation Partnership Project
AM	Amplitude Modulation
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
LTE	Long Term Evolution
MTF	Median Time to Failure
OBO	Output Back Off
PAR	Peak-to-Average Ratio
PM	Phase Modulation
RoHS	Restriction of Hazardous Substances
SMD	Surface Mounted Device
VBW	Video BandWidth
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

11. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLC10G27XS-551AVT v.1	20190920	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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For sales office addresses, please visit: <http://www.ampleon.com/sales>

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